Lattice Semiconductor Corporation - LFE2-6SE-6F256C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	750
Number of Logic Elements/Cells	6000
Total RAM Bits	56320
Number of I/O	190
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-6se-6f256c

this special vertical routing channel and the eight secondary clock regions for the ECP2-50. LatticeECP2 devices have four secondary clocks (SC0 to SC3) which are distrubed to every region.

The secondary clock muxes are located in the center of the device. Figure 2-16 shows the mux structure of the secondary clock routing. Secondary clocks SC0 to SC3 are used for clock and control and SC4 to SC7 are used for high fan-out signals.

Figure 2-15. Secondary Clock Regions ECP2-50

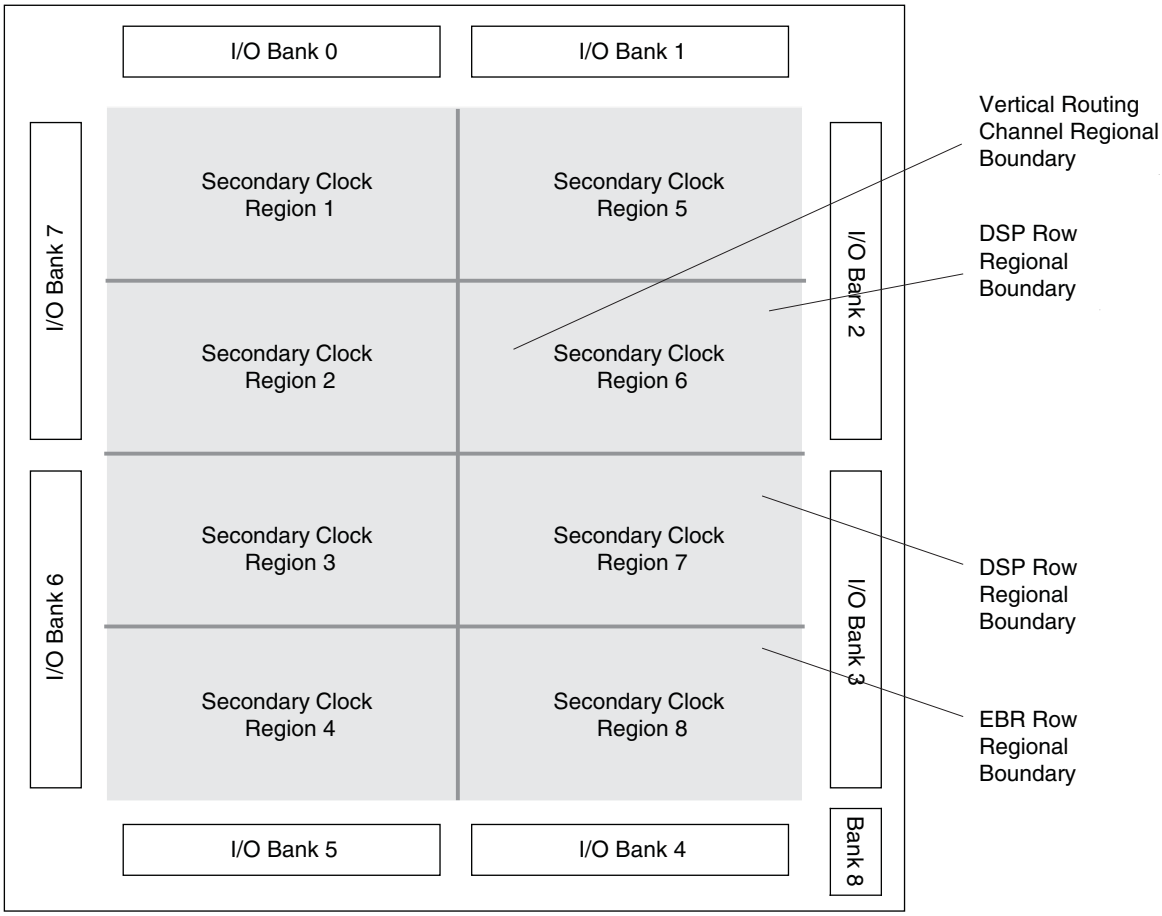
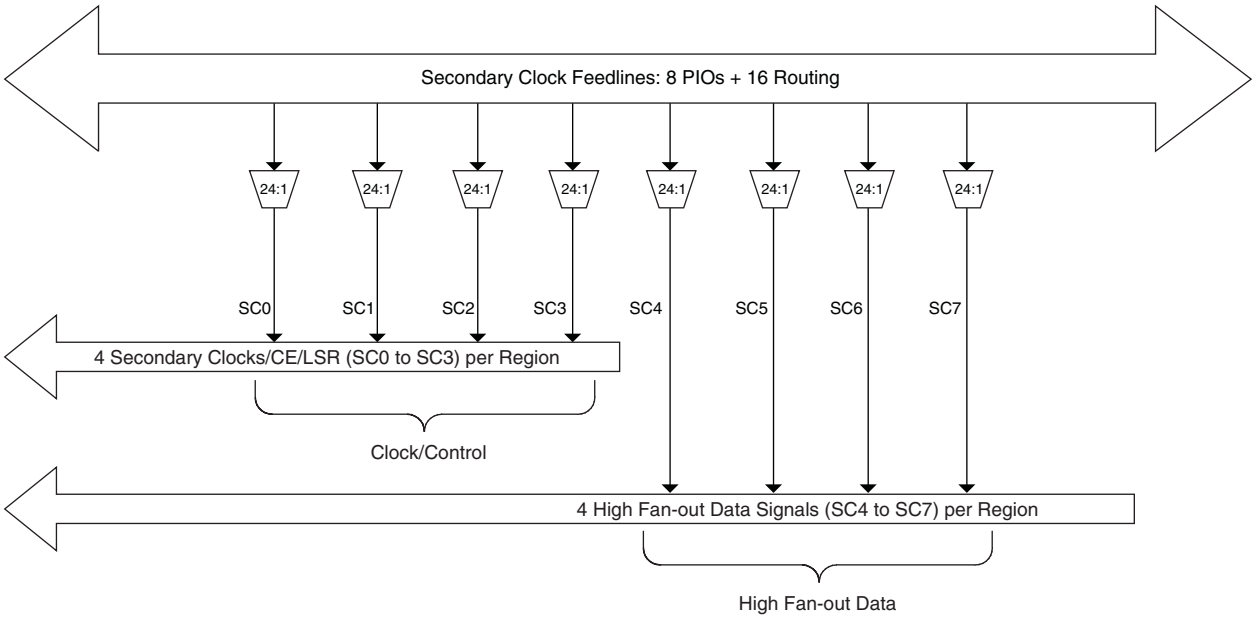


Figure 2-16. Secondary Clock Selection



Slice Clock Selection

Figure 2-17 shows the clock selections and Figure 2-18 shows the control selections for Slice0 through Slice2. All the primary clocks and the four secondary clocks are routed to this clock selection mux. Other signals can be used as a clock input to the slices via routing. Slice controls are generated from the secondary clocks or other signals connected via routing.

If none of the signals are selected for both clock and control then the default value of the mux output is 1. Slice 3 does not have any registers; therefore it does not have the clock or control muxes.

Figure 2-17. Slice0 through Slice2 Clock Selection

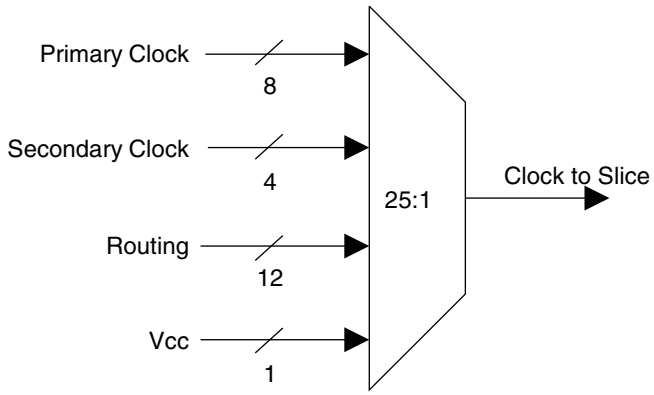
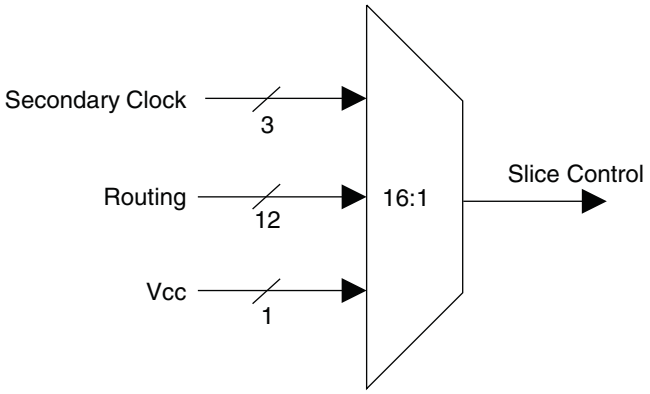


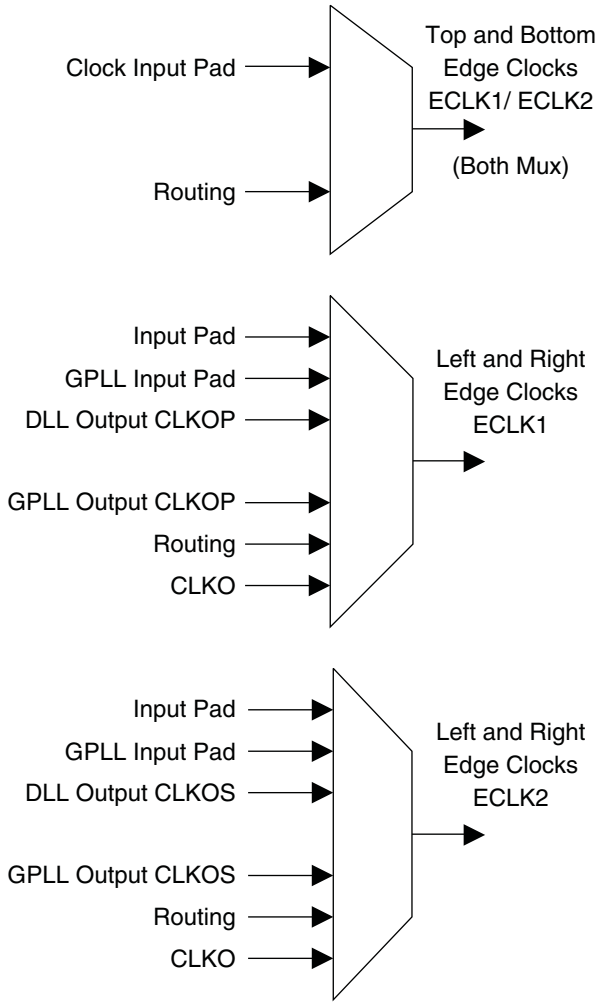
Figure 2-18. Slice0 through Slice2 Control Selection



Edge Clock Routing

LatticeECP2/M devices have a number of high-speed edge clocks that are intended for use with the PIOs in the implementation of high-speed interfaces. There are eight edge clocks per device: two edge clocks per edge. Different PLL and DLL outputs are routed to the two muxes on the left and right sides of the device. In addition, the CLKO signal (generated from the DLLDELA block) is routed to all the edge clock muxes on the left and right sides of the device. Figure 2-19 shows the selection muxes for these clocks.

Figure 2-19. Edge Clock Mux Connections



sysMEM Memory

LatticeECP2/M devices contains a number of sysMEM Embedded Block RAM (EBR). The EBR consists of an 18-Kbit RAM with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6. FIFOs can be implemented in sysMEM EBR blocks by implementing support logic with PFUs. The EBR block facilitates parity checking by supporting an optional parity bit for each data byte. EBR blocks provide byte-enable support for configurations with18-bit and 36-bit data widths.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
True Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18
Pseudo Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1, and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Memory Cascading

Larger and deeper blocks of RAM can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output.

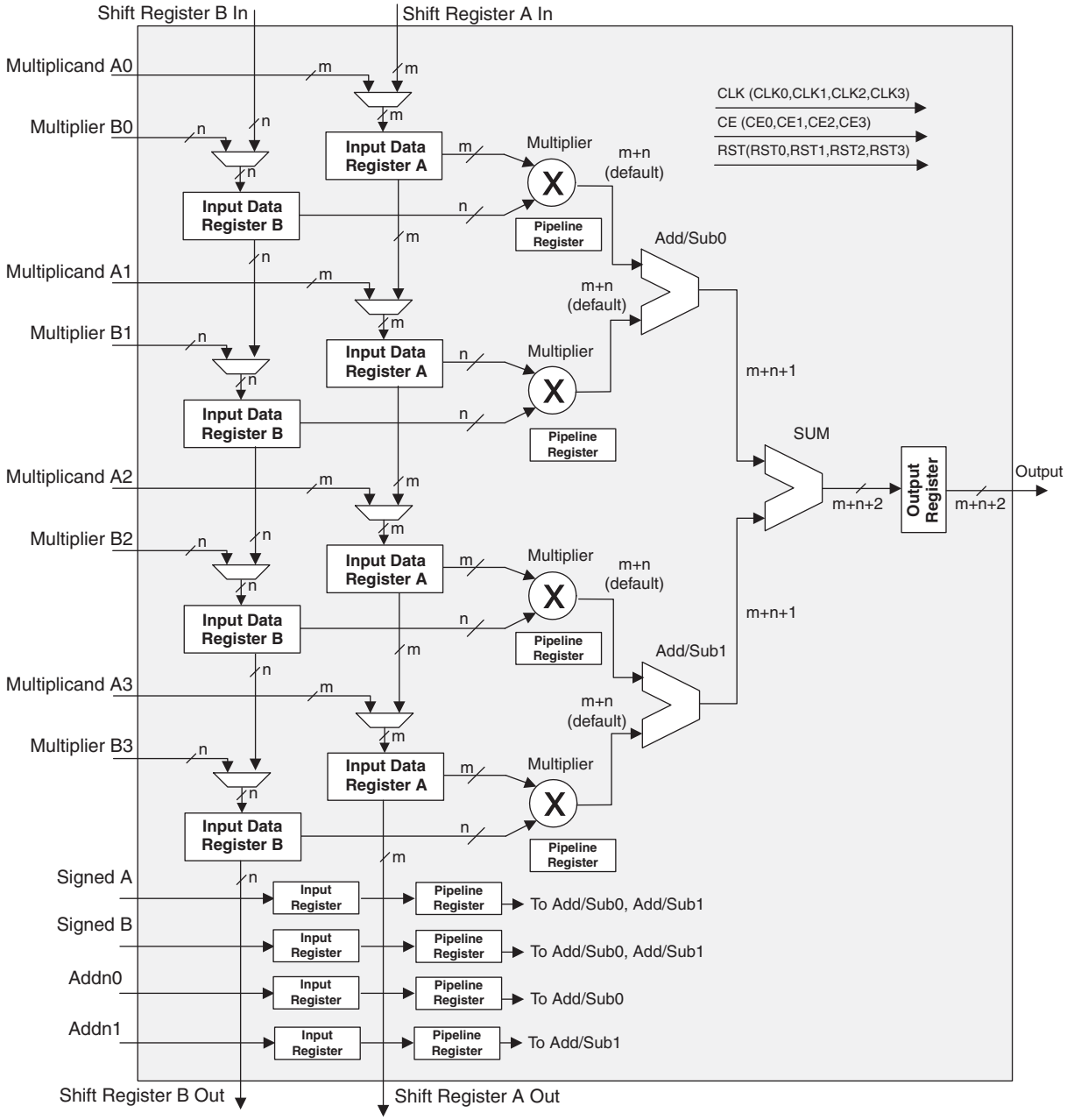
EBR memory supports two forms of write behavior for single port or dual port operation:

1. Normal – Data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

MULTADDSUBSUM sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and B1. Additionally the operands A2 and B2 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A3 and B3. The result of both addition/subtraction are added in a summation block. The user can enable the input, output and pipeline registers. Figure 2-26 shows the MULTADDSUBSUM sysDSP element.

Figure 2-26. MULTADDSUBSUM



Clock, Clock Enable and Reset Resources

Global Clock, Clock Enable and Reset signals from routing are available to every DSP block. Four Clock, Reset and Clock Enable signals are selected for the sysDSP block. From four clock sources (CLK0, CLK1, CLK2, CLK3)

LatticeECP2M Supply Current (Standby)[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5]	Units
I_{CC}	Core Power Supply Current	ECP2M20	25	mA
		ECP2M35	50	mA
		ECP2M50	85	mA
		ECP2M70	100	mA
		ECP2M100	100	mA
I_{CCAUX}	Auxiliary Power Supply Current	ECP2M20	24	mA
		ECP2M35	24	mA
		ECP2M50	24	mA
		ECP2M70	24	mA
		ECP2M100	24	mA
I_{CCGPLL}	GPLL Power Supply Current (per GPLL)	All Devices	0.5	mA
I_{CCSPLL}	GPLL Power Supply Current (per SPLL)	All Devices	0.5	mA
I_{CCIO}	Bank Power Supply Current (Per Bank)	ECP2M20	2	mA
		ECP2M35	2	mA
		ECP2M50	2	mA
		ECP2M70	2	mA
		ECP2M100	2	mA
I_{CCJ}	V_{CCJ} Power Supply Current	All Devices	3	mA

1. For further information about supply current, please see the list of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
3. Frequency 0MHz.
4. Pattern represents a “blank” configuration data file.
5. T_J = 25°C, power supplies at normal voltage.

LatticeECP2 Initialization Supply Current[1, 2, 3, 4]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[5, 6, 7]	Units
I_{CC}	Core Power Supply Current	ECP2-6	34	mA
		ECP2-12	54	mA
		ECP2-20	82	mA
		ECP2-35	135	mA
		ECP2-50	187	mA
		ECP2-70	267	mA
I_{CCAUX}	Auxiliary Power Supply Current	ECP2-6	30	mA
		ECP2-12	30	mA
		ECP2-20	30	mA
		ECP2-35	30	mA
		ECP2-50	30	mA
		ECP2-70	30	mA
I_{CCGPLL}	GPLL Power Supply Current (per GPLL)	ECP2-35, -50, -70 Only	0.5	mA
I_{CCSPLL}	SPLL Power Supply Current (per SPLL)	ECP2-35, -50, -70 Only	0.5	mA
I_{CCIO}	Bank Power Supply Current (per Bank)	All Devices	3	mA
I_{CCJ}	VCCJ Power Supply Current	All Devices	4	mA

1. Until DONE signal is active.
2. For further information about supply current, please see the list of additional technical documentation at the end of this data sheet.
3. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
4. Frequency 0MHz.
5. T_J = 25°C, power supplies at nominal voltage.
6. A specific configuration pattern is used that scales with the size of the device; consists of 75% PFU utilization, 50% EBR, and 25% I/O configuration.
7. Values shown in this column are the typical average DC current during configuration. Use the Power Calculator tool to find the peak startup current.

LatticeECP2/M Family Timing Adders[1, 2, 3] (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-7	-6	-5	Units
LVCMOS25_4mA	LVCMOS 2.5 4mA drive, slow slew rate	2.18	2.26	2.33	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive, slow slew rate	2.19	2.35	2.51	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive, slow slew rate	1.50	1.66	1.82	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive, slow slew rate	1.60	1.59	1.58	ns
LVCMOS25_20mA	LVCMOS 2.5 20mA drive, slow slew rate	1.43	1.39	1.34	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive, slow slew rate	2.22	2.27	2.32	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive, slow slew rate	1.93	2.08	2.23	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive, slow slew rate	1.43	1.51	1.58	ns
LVCMOS18_16mA	LVCMOS 1.8 16mA drive, slow slew rate	1.47	1.46	1.45	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive, slow slew rate	2.32	2.38	2.43	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive, slow slew rate	1.84	1.98	2.12	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive, slow slew rate	2.52	2.63	2.74	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive, slow slew rate	1.69	1.83	1.96	ns
PCI33	PCI33	0.04	0.04	0.04	ns

1. Timing Adders are characterized but not tested on every device.
2. LVCMOS timing measured with the load specified in Switching Test Condition table.
3. All other standards tested according to the appropriate specifications.
4. These timing adders are measured with the recommended resistor values.

Timing v.A 0.11

LatticeECP2 Pin Information Summary, LFE2-6 and LFE2-12

Pin Type		LFE2-6		LFE2-12			
		144 TQFP	256 fpBGA	144 TQFP	208 PQFP	256 fpBGA	484 fpBGA
Single Ended User I/O		90	190	93	131	193	297
Differential Pair User I/O		43	95	45	62	96	148
Configuration	TAP Pins	5	5	5	5	5	5
	Muxed Pins	14	14	14	14	14	14
	Dedicated Pins (Non TAP)	7	7	7	7	7	7
Non Configuration	Muxed Pins	34	54	33	40	54	57
	Dedicated Pins	3	3	3	3	3	3
VCC		10	7	10	14	7	16
VCCAUX		4	4	4	8	4	16
VCCPLL		0	0	0	0	0	0
VCCIO	Bank0	1	2	1	2	2	4
	Bank1	1	2	1	2	2	4
	Bank2	1	2	1	2	2	4
	Bank3	1	2	1	2	2	4
	Bank4	1	2	1	2	2	4
	Bank5	1	2	1	2	2	4
	Bank6	1	2	1	2	2	4
	Bank7	1	2	1	2	2	4
	Bank8	1	1	1	2	1	2
GND, GND0 to GND7		12	20	12	22	20	60
NC		4	3	1	0	0	44
Single Ended/ Differential I/O Pairs per Bank (including emulated with resistors)	Bank0	8/4	18/6	8/4	18/9	18/9	50/25
	Bank1	17/8	34/17	18/9	18/9	34/17	46/23
	Bank2	4/2	20/10	4/2	11/5	20/10	24/12
	Bank3	8/4	12/6	8/4	11/5	12/6	16/8
	Bank4	18/9	32/16	18/9	19/9	32/16	46/23
	Bank5	8/4	14/7	10/5	18/9	17/8	46/23
	Bank6	9/4	26/13	9/4	18/8	26/13	32/16
	Bank7	12/6	20/10	12/6	12/6	20/10	23/11
	Bank8	6/2	14/7	6/2	6/2	14/7	14/7
True LVDS I/O Pairs per Bank	Bank0 (Top Edge)	0	0	0	0	0	0
	Bank1 (Top Edge)	0	0	0	0	0	0
	Bank2 (Right Edge)	1	5	1	4	5	6
	Bank3 (Right Edge)	3	3	3	3	3	4
	Bank4 (Bottom Edge)	0	0	0	0	0	0
	Bank5 (Bottom Edge)	0	0	0	0	0	0
	Bank6 (Left Edge)	2	7	2	6	7	8
	Bank7 (Left Edge)	5	5	5	5	5	5
	Bank8 (Right Edge)	0	0	0	0	0	0

LatticeECP2 Pin Information Summary, LFE2-20 and LFE2-35

Pin Type		LFE2-20				LFE2-35	
		208 PQFP	256 fpBGA	484 fpBGA	672 fpBGA	484 fpBGA	672 fpBGA
Single Ended User I/O		131	193	331	402	331	450
Differential Pair User I/O		62	96	165	200	165	224
Configuration	TAP Pins	5	5	5	5	5	5
	Muxed Pins	14	14	14	14	14	14
	Dedicated Pins (Non TAP)	7	7	7	7	7	7
Non Configuration	Muxed Pins	42	54	60	64	60	68
	Dedicated Pins	3	3	3	3	3	3
VCC		14	7	18	24	16	22
VCCAUX		8	4	16	16	16	16
VCCPLL		0	0	0	0	2	2
VCCIO	Bank0	2	2	4	5	4	5
	Bank1	2	2	4	5	4	5
	Bank2	2	2	4	5	4	5
	Bank3	2	2	4	5	4	5
	Bank4	2	2	4	5	4	5
	Bank5	2	2	4	5	4	5
	Bank6	2	2	4	5	4	5
	Bank7	2	2	4	5	4	5
	Bank8	2	1	2	2	2	2
GND, GND0 to GND7		22	20	60	72	60	72
NC		0	1	8	101	8	102
Single Ended/ Differential I/O Pairs per Bank (including emulated with resistors)	Bank0	18/9	18/9	50/25	67/33	50/25	67/33
	Bank1	18/9	34/17	46/23	52/26	46/23	52/26
	Bank2	11/5	20/10	34/17	36/18	34/17	48/24
	Bank3	11/5	12/6	22/11	32/16	22/11	42/21
	Bank4	19/9	32/16	46/23	50/25	46/23	54/27
	Bank5	18/9	17/8	46/23	68/34	46/23	68/34
	Bank6	18/8	26/13	40/20	48/24	40/20	58/29
	Bank7	12/6	20/10	33/16	35/17	33/16	47/23
	Bank8	6/2	14/7	14/7	14/7	14/7	14/7
True LVDS I/O Pairs per Bank	Bank0 (Top Edge)	0	0	0	0	0	0
	Bank1 (Top Edge)	0	0	0	0	0	0
	Bank2 (Right Edge)	4	5	9	9	9	12
	Bank3 (Right Edge)	3	3	5	8	5	9
	Bank4 (Bottom Edge)	0	0	0	0	0	0
	Bank5 (Bottom Edge)	0	0	0	0	0	0
	Bank6 (Left Edge)	6	7	10	12	10	13
	Bank7 (Left Edge)	5	5	8	8	8	11
	Bank8 (Right Edge)	0	0	0	0	0	0

LatticeECP2M Power Supply and NC

Signal	256 fpBGA	484 fpBGA
V_{CC}	G7, G9, H7, J10, K10, K8	J10, J11, J12, J13, K14, K9, L14, L9, M14, M9, N14, N9, P10, P11, P12, P13
V_{CCIO0}	E7	B5, B9, E7, H9
V_{CCIO1}	E10	D13, E16, H14
V_{CCIO2}	E14, G12	E21, G18, J15, K19
V_{CCIO3}	K12, M14	N19, P15, T18, V21
V_{CCIO4}	M10, P12	AA18, R14, V16, W13
V_{CCIO5}	M7, P5	AA5, R9, V7, W10
V_{CCIO6}	K5, M3	N4, P8, T5, V2
V_{CCIO7}	E3, G5	E2, G5, J8, K4
V_{CCIO8}	T15	AA22, U19
V_{CCJ}	K7	W4
V_{CCAUX}	G8, H10, J7, K9	H11, H12, L15, L8, M15, M8, R11, R12
V_{CCPLL}	G10	R8, H15, H8, R15
SERDES Power[3]	C15, B15, C12, A12, C11, C10, C14, C13, B9, C9, C5, C4, C8, C7, A6, C6, B3, C3	C22, B22, C19, A19, C18, C17, C21, C20, B16, C16, C12, C11, C15, C14, A13, C13, B10, C10
GND[1]	A1, A15, A16, A3, A9, B12, B6, E15, E2, H14, H8, H9, J3, J8, J9, M15, M2, P9, R12, R5, T1, T16	A1, A10, A16, A22, AA19, AA4, AB1, AB22, B13, B19, B4, D16, D2, D21, D7, G19, G4, H10, H13, J14, J9, K10, K11, K12, K13, K15, K20, K3, K8, L10, L11, L12, L13, M10, M11, M12, M13, N10, N11, N12, N13, N15, N20, N3, N8, P14, P9, R10, R13, T19, T4, W16, W2, W21, W7, Y10, Y13
NC[2]	D10, D11, D12, D13, D14, D4, D5, D6, D7, E11, E6, E8, E9, F10, F7, F8, F9	**LFE2M20:** D14, D15, E14, E15, F13, F14, F15, G12, G13, G14, G15 **LFE2M35:** D14, D15, E14, E15, F13, F14, F15, G12, G13, G14, G15, U6 **LFE2M50:** Y15, W15, AB20, AB21, AA20, AB19, AB18, Y22, Y21, Y17, Y18, Y16, W17, Y19, Y20, W19, W18, V17, V18, D15, G14, G15, D14, E15, E14, F15, F14, F13, G12, G13

1. All grounds must be electrically connected at the board level. For fpBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
2. NC pins should not be connected to any active signals, VCC or GND.
3. For package migration across device densities, the designer must comprehend the package pin requirements for the SERDES blocks. Specifically, the SERDES power pins of the largest density device must be accounted to accommodate migration to other smaller devices using the same package. Please refer to TN1160, LatticeECP2/M Density Migration for more details.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
W19	CFG2	8			CFG2	8		
V19	CFG1	8			CFG1	8		
V20	PROGRAMN	8			PROGRAMN	8		
W20	CFG0	8			CFG0	8		
U22	PR28B	8	D1	C	PR42B	8	D1	C
V22	INITN	8			INITN	8		
R16	PR30B	8	WRITEN	C	PR44B	8	WRITEN	C
GNDIO	GNDIO8	-			GNDIO8	-		
W22	CCLK	8			CCLK	8		
R17	PR30A	8	CS1N	T	PR44A	8	CS1N	T
V21	DONE	8			DONE	8		
VCCIO	VCCIO8	8			VCCIO8	8		
U19	PR29B	8	CSN	C	PR43B	8	CSN	C
T17	PR26B	8	D5	C	PR40B	8	D5	C
U20	PR29A	8	D0/SPIFASTN	T	PR43A	8	D0/SPIFASTN	T
U21	PR28A	8	D2	T	PR42A	8	D2	T
GNDIO	GNDIO8	-			GNDIO8	-		
T18	PR26A	8	D6	T	PR40A	8	D6	T
T20	PR27B	8	D3	C	PR41B	8	D3	C
T21	PR25B	8	D7/SPID0	C	PR39B	8	D7/SPID0	C
T19	PR27A	8	D4	T	PR41A	8	D4	T
VCCIO	VCCIO8	8			VCCIO8	8		
T22	PR25A	8	DI/CSSPI0N	T	PR39A	8	DI/CSSPI0N	T
R18	PR24B	8	DOUT/CSON	C	PR38B	8	DOUT/CSON	C
R19	PR24A	8	BUSY/SISPI	T	PR38A	8	BUSY/SISPI	T
-	-	-			VCCIO3	3		
GNDIO	GNDIO3	-			GNDIO3	-		
P18	PR22B	3		C (LVDS)*	PR32B	3	RDQ34	C (LVDS)*
R22	PR23B	3		C	PR33B	3	RDQ34	C
P19	PR22A	3		T (LVDS)*	PR32A	3	RDQ34	T (LVDS)*
R21	PR23A	3		T	PR33A	3	RDQ34	T
VCCIO	VCCIO3	3			VCCIO3	3		
R20	PR21B	3	RLM0_GPLLC_FB_A	C	PR31B	3	RLM0_GPLLC_FB_A/RDQ34	C
P22	PR21A	3	RLM0_GPLLT_FB_A	T	PR31A	3	RLM0_GPLLT_FB_A/RDQ34	T
P21	PR20B	3	RLM0_GPLLC_IN_A**	C (LVDS)*	PR30B	3	RLM0_GPLLC_IN_A**/RDQ34	C (LVDS)*
N21	PR20A	3	RLM0_GPLLT_IN_A**	T (LVDS)*	PR30A	3	RLM0_GPLLT_IN_A**/RDQ34	T (LVDS)*
N17	RLM0_PLLCAP	3			RLM0_PLLCAP	3		
N22	PR18B	3	RLM0_GDLLC_FB_A	C	PR28B	3	RLM0_GDLLC_FB_A/RDQ25	C
M22	PR17B	3	RLM0_GDLLC_IN_A**	C (LVDS)*	PR27B	3	RLM0_GDLLC_IN_A**/RDQ25	C (LVDS)*
GNDIO	GNDIO3	-			GNDIO3	-		
N20	PR18A	3	RLM0_GDLLT_FB_A	T	PR28A	3	RLM0_GDLLT_FB_A/RDQ25	T
M21	PR17A	3	RLM0_GDLLT_IN_A**	T (LVDS)*	PR27A	3	RLM0_GDLLT_IN_A**/RDQ25	T (LVDS)*
N19	NC	-			PR26B	3	RDQ25	C
-	-	-			VCCIO3	3		

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2-12E/12SE					LFE2-20E/20SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
J9	GND	-			GND	-		
K10	GND	-			GND	-		
K11	GND	-			GND	-		
K12	GND	-			GND	-		
K13	GND	-			GND	-		
K15	GND	-			GND	-		
K8	GND	-			GND	-		
L10	GND	-			GND	-		
L11	GND	-			GND	-		
L12	GND	-			GND	-		
L13	GND	-			GND	-		
L15	GND	-			GND	-		
L8	GND	-			GND	-		
M10	GND	-			GND	-		
M11	GND	-			GND	-		
M12	GND	-			GND	-		
M13	GND	-			GND	-		
M15	GND	-			GND	-		
M8	GND	-			GND	-		
N10	GND	-			GND	-		
N11	GND	-			GND	-		
N12	GND	-			GND	-		
N13	GND	-			GND	-		
N15	GND	-			GND	-		
N8	GND	-			GND	-		
P14	GND	-			GND	-		
P20	GND	-			GND	-		
P3	GND	-			GND	-		
P9	GND	-			GND	-		
R10	GND	-			GND	-		
R11	GND	-			GND	-		
R12	GND	-			GND	-		
R13	GND	-			GND	-		
U17	GND	-			GND	-		
U6	GND	-			GND	-		
W2	GND	-			GND	-		
W21	GND	-			GND	-		
Y14	GND	-			GND	-		
Y9	GND	-			GND	-		
H6	NC	-			NC	-		
J6	NC	-			NC	-		
H3	NC	-			NC	-		
H2	NC	-			NC	-		
H17	NC	-			NC	-		

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
W5	PL71B	6	LDQ75	C (LVDS)*	PL84B	6	LDQ88	C (LVDS)*
AC1	PL72A	6	LDQ75	T	PL85A	6	LDQ88	T
AD1	PL72B	6	LDQ75	C	PL85B	6	LDQ88	C
VCCIO	VCCIO6	6			VCCIO6	6		
Y6	PL73A	6	LDQ75	T (LVDS)*	PL86A	6	LDQ88	T (LVDS)*
Y5	PL73B	6	LDQ75	C (LVDS)*	PL86B	6	LDQ88	C (LVDS)*
AE2	PL74A	6	LDQ75	T	PL87A	6	LDQ88	T
AD2	PL74B	6	LDQ75	C	PL87B	6	LDQ88	C
GND	GNDIO6	-			GNDIO6	-		
AB3	PL75A	6	LDQS75	T (LVDS)*	PL88A	6	LDQS88	T (LVDS)*
AB2	PL75B	6	LDQ75	C (LVDS)*	PL88B	6	LDQ88	C (LVDS)*
W7	PL76A	6	LDQ75	T	PL89A	6	LDQ88	T
VCCIO	VCCIO6	6			VCCIO6	6		
W8	PL76B	6	LDQ75	C	PL89B	6	LDQ88	C
Y7	PL77A	6	LDQ75	T (LVDS)*	PL90A	6	LDQ88	T (LVDS)*
Y8	PL77B	6	LDQ75	C (LVDS)*	PL90B	6	LDQ88	C (LVDS)*
AC2	PL78A	6	LDQ75	T	PL91A	6	LDQ88	T
GND	GNDIO6	-			GNDIO6	-		
AD3	PL78B	6	LDQ75	C	PL91B	6	LDQ88	C
AC3	TCK	-			TCK	-		
AA8	TDI	-			TDI	-		
AB4	TMS	-			TMS	-		
AA5	TDO	-			TDO	-		
AB5	VCCJ	-			VCCJ	-		
AE3	PB2A	5	VREF2_5/BDQ6	T	PB2A	5	VREF2_5/BDQ6	T
AF3	PB2B	5	VREF1_5/BDQ6	C	PB2B	5	VREF1_5/BDQ6	C
AC4	PB3A	5	BDQ6	T	PB3A	5	BDQ6	T
AD4	PB3B	5	BDQ6	C	PB3B	5	BDQ6	C
AE4	PB4A	5	BDQ6	T	PB4A	5	BDQ6	T
AF4	PB4B	5	BDQ6	C	PB4B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
V9	PB5A	5	BDQ6	T	PB5A	5	BDQ6	T
W9	PB5B	5	BDQ6	C	PB5B	5	BDQ6	C
GND	GNDIO5	-			GNDIO5	-		
AA6	PB6A	5	BDQS6	T	PB6A	5	BDQS6	T
AB6	PB6B	5	BDQ6	C	PB6B	5	BDQ6	C
AC5	PB7A	5	BDQ6	T	PB7A	5	BDQ6	T
AD5	PB7B	5	BDQ6	C	PB7B	5	BDQ6	C
AA7	PB8A	5	BDQ6	T	PB8A	5	BDQ6	T
AB7	PB8B	5	BDQ6	C	PB8B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		
AE5	PB9A	5	BDQ6	T	PB9A	5	BDQ6	T
AF5	PB9B	5	BDQ6	C	PB9B	5	BDQ6	C
AC7	PB10A	5	BDQ6	T	PB10A	5	BDQ6	T
AD7	PB10B	5	BDQ6	C	PB10B	5	BDQ6	C
VCCIO	VCCIO5	5			VCCIO5	5		

LFE2M-20E/SE and LFE2M-35E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
F14	PR24B	2	RDQ22	C (LVDS)*	PR34B	2	RDQ32	C(LVDS)*
F13	PR24A	2	RDQ22	T (LVDS)*	PR34A	2	RDQ32	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO2	2		
GNDIO	GNDIO2	-			GNDIO2	-		
H11	PR14B	2		C	PR14B	2	RDQ15	C
G11	PR14A	2		T	PR14A	2	RDQ15	T
E13	PR13B	2		C (LVDS)*	PR13B	2	RDQ15	C(LVDS)*
F12	PR13A	2		T (LVDS)*	PR13A	2	RDQ15	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO2	2		
F11	PR12B	2	RUM0_SPLLC_FB_A	C	PR12B	2	RUM0_SPLLC_FB_A/RDQ15	C
E12	PR12A	2	RUM0_SPLLT_FB_A	T	PR12A	2	RUM0_SPLLT_FB_A/RDQ15	T
D16	PR11B	2	RUM0_SPLLC_IN_A	C (LVDS)*	PR11B	2	RUM0_SPLLC_IN_A/RDQ15	C(LVDS)*
D15	PR11A	2	RUM0_SPLLT_IN_A	T (LVDS)*	PR11A	2	RUM0_SPLLT_IN_A/RDQ15	T (LVDS)*
C16	PR9B	2	VREF2_2	C	PR9B	2	VREF2_2	C
GNDIO	GNDIO2	-			GNDIO2	-		
B16	PR9A	2	VREF1_2	T	PR9A	2	VREF1_2	T
VCCIO	VCCIO2	2			VCCIO2	2		
F4	XRES	-			XRES	-		
C15	URC_SQ_VCCRX0	12			URC_SQ_VCCRX0	12		
A14	URC_SQ_HDINP0	12		T	URC_SQ_HDINP0	12		T
B15	URC_SQ_VCCIB0	12			URC_SQ_VCCIB0	12		
B14	URC_SQ_HDINN0	12		C	URC_SQ_HDINN0	12		C
C12	URC_SQ_VCCTX0	12			URC_SQ_VCCTX0	12		
A11	URC_SQ_HDOUTP0	12		T	URC_SQ_HDOUTP0	12		T
A12	URC_SQ_VCCOB0	12			URC_SQ_VCCOB0	12		
B11	URC_SQ_HDOUTN0	12		C	URC_SQ_HDOUTN0	12		C
C11	URC_SQ_VCCTX1	12			URC_SQ_VCCTX1	12		
B10	URC_SQ_HDOUTN1	12		C	URC_SQ_HDOUTN1	12		C
C10	URC_SQ_VCCOB1	12			URC_SQ_VCCOB1	12		
A10	URC_SQ_HDOUTP1	12		T	URC_SQ_HDOUTP1	12		T
C14	URC_SQ_VCCRX1	12			URC_SQ_VCCRX1	12		
B13	URC_SQ_HDINN1	12		C	URC_SQ_HDINN1	12		C
C13	URC_SQ_VCCIB1	12			URC_SQ_VCCIB1	12		
A13	URC_SQ_HDINP1	12		T	URC_SQ_HDINP1	12		T
B9	URC_SQ_VCCAUX33	12			URC_SQ_VCCAUX33	12		
D8	URC_SQ_REFCLKN	12		C	URC_SQ_REFCLKN	12		C
D9	URC_SQ_REFCLKP	12		T	URC_SQ_REFCLKP	12		T
C9	URC_SQ_VCCP	12			URC_SQ_VCCP	12		
A5	URC_SQ_HDINP2	12		T	URC_SQ_HDINP2	12		T
C5	URC_SQ_VCCIB2	12			URC_SQ_VCCIB2	12		
B5	URC_SQ_HDINN2	12		C	URC_SQ_HDINN2	12		C
C4	URC_SQ_VCCRX2	12			URC_SQ_VCCRX2	12		
A8	URC_SQ_HDOUTP2	12		T	URC_SQ_HDOUTP2	12		T
C8	URC_SQ_VCCOB2	12			URC_SQ_VCCOB2	12		
B8	URC_SQ_HDOUTN2	12		C	URC_SQ_HDOUTN2	12		C
C7	URC_SQ_VCCTX2	12			URC_SQ_VCCTX2	12		
B7	URC_SQ_HDOUTN3	12		C	URC_SQ_HDOUTN3	12		C
A6	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12		

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GNDIO	GNDIO7	-			GNDIO7	-		
K5	PL23A	7	LDQS23	T (LVDS)*	PL27A	7	LDQS27	T*
L5	PL23B	7	LDQ23	C (LVDS)*	PL27B	7	LDQ27	C*
K4	PL24A	7	LDQ23	T	PL28A	7	LDQ27	T
VCCIO	VCCIO7	7			VCCIO7	7		
L4	PL24B	7	LDQ23	C	PL28B	7	LDQ27	C
K3	PL25A	7	LDQ23	T (LVDS)*	PL29A	7	LDQ27	T*
L3	PL25B	7	LDQ23	C (LVDS)*	PL29B	7	LDQ27	C*
J1	PL26A	7	LDQ23	T	PL30A	7	LDQ27	T
GNDIO	GNDIO7	-			GNDIO7	-		
K2	PL26B	7	LDQ23	C	PL30B	7	LDQ27	C
K1	PL28A	7	LUM1_SPLLT_IN_A/LDQ32	T (LVDS)*	PL32A	7	LUM3_SPLLT_IN_A/LDQ36	T*
L1	PL28B	7	LUM1_SPLLC_IN_A/LDQ32	C (LVDS)*	PL32B	7	LUM3_SPLLC_IN_A/LDQ36	C*
K8	PL29A	7	LUM1_SPLLT_FB_A/LDQ32	T	PL33A	7	LUM3_SPLLT_FB_A/LDQ36	T
M5	PL29B	7	LUM1_SPLLC_FB_A/LDQ32	C	PL33B	7	LUM3_SPLLC_FB_A/LDQ36	C
VCCIO	VCCIO7	7			VCCIO7	7		
M4	PL30A	7	LDQ32	T (LVDS)*	PL34A	7	LDQ36	T*
M3	PL30B	7	LDQ32	C (LVDS)*	PL34B	7	LDQ36	C*
L8	PL31A	7	LDQ32	T	PL35A	7	LDQ36	T
M6	PL31B	7	LDQ32	C	PL35B	7	LDQ36	C
GNDIO	GNDIO7	-			GNDIO7	-		
M1	PL32A	7	LDQS32	T (LVDS)*	PL36A	7	LDQS36	T*
N1	PL32B	7	LDQ32	C (LVDS)*	PL36B	7	LDQ36	C*
N3	PL33A	7	LDQ32	T	PL37A	7	LDQ36	T
VCCIO	VCCIO7	7			VCCIO7	7		
N2	PL33B	7	LDQ32	C	PL37B	7	LDQ36	C
N5	PL34A	7	LDQ32	T (LVDS)*	PL38A	7	LDQ36	T*
N4	PL34B	7	LDQ32	C (LVDS)*	PL38B	7	LDQ36	C*
M7	PL35A	7	PCLKT7_0/LDQ32	T	PL39A	7	PCLKT7_0/LDQ36	T
GNDIO	GNDIO7	-			GNDIO7	-		
M8	PL35B	7	PCLKC7_0/LDQ32	C	PL39B	7	PCLKC7_0/LDQ36	C
P3	PL37A	6	PCLKT6_0	T (LVDS)*	PL41A	6	PCLKT6_0	T*
P2	PL37B	6	PCLKC6_0	C (LVDS)*	PL41B	6	PCLKC6_0	C*
P5	PL38A	6	VREF2_6	T	PL42A	6	VREF2_6	T
N6	PL38B	6	VREF1_6	C	PL42B	6	VREF1_6	C
P4	PL39A	6		T (LVDS)*	PL43A	6		T*
VCCIO	VCCIO6	6			VCCIO6	6		
R3	PL39B	6		C (LVDS)*	PL43B	6		C*
P6	PL40A	6		T	PL44A	6		T
N7	NC	-			PL44B	6		C
P1	PL41A	6	LLM2_SPLLT_IN_A	T (LVDS)*	PL45A	6	LLM3_SPLLT_IN_A	T*
GNDIO	GNDIO6	-			GNDIO6	-		
R1	PL41B	6	LLM2_SPLLC_IN_A	C (LVDS)*	PL45B	6	LLM3_SPLLC_IN_A	C*
N8	PL42A	6	LLM2_SPLLT_FB_A	T	PL46A	6	LLM3_SPLLT_FB_A	T
R5	PL42B	6	LLM2_SPLLC_FB_A	C	PL46B	6	LLM3_SPLLC_FB_A	C
VCCIO	VCCIO6	6			VCCIO6	6		
T3	PL44A	6	LDQ48	T (LVDS)*	PL48A	6	LDQ52	T*
T4	PL44B	6	LDQ48	C (LVDS)*	PL48B	6	LDQ52	C*

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AN29	LRC_SQ_VCCRX2	13			LRC_SQ_VCCRX2	13		
AM28	LRC_SQ_HDINN2	13		C	LRC_SQ_HDINN2	13		C
AL27	LRC_SQ_VCCIB2	13			LRC_SQ_VCCIB2	13		
AM29	LRC_SQ_HDINP2	13		T	LRC_SQ_HDINP2	13		T
AL29	LRC_SQ_VCCP	13			LRC_SQ_VCCP	13		
AL30	LRC_SQ_REFCLKP	13		T	LRC_SQ_REFCLKP	13		T
AK30	LRC_SQ_REFCLKN	13		C	LRC_SQ_REFCLKN	13		C
AK29	LRC_SQ_VCCAUX33	13			LRC_SQ_VCCAUX33	13		
AM30	LRC_SQ_HDINP1	13		T	LRC_SQ_HDINP1	13		T
AL31	LRC_SQ_VCCIB1	13			LRC_SQ_VCCIB1	13		
AM31	LRC_SQ_HDINN1	13		C	LRC_SQ_HDINN1	13		C
AN30	LRC_SQ_VCCRX1	13			LRC_SQ_VCCRX1	13		
AP30	LRC_SQ_HDOUTP1	13		T	LRC_SQ_HDOUTP1	13		T
AL32	LRC_SQ_VCCOB1	13			LRC_SQ_VCCOB1	13		
AP31	LRC_SQ_HDOUTN1	13		C	LRC_SQ_HDOUTN1	13		C
AN31	LRC_SQ_VCCTX1	13			LRC_SQ_VCCTX1	13		
AP32	LRC_SQ_HDOUTN0	13		C	LRC_SQ_HDOUTN0	13		C
AM34	LRC_SQ_VCCOB0	13			LRC_SQ_VCCOB0	13		
AP33	LRC_SQ_HDOUTP0	13		T	LRC_SQ_HDOUTP0	13		T
AN32	LRC_SQ_VCCTX0	13			LRC_SQ_VCCTX0	13		
AM32	LRC_SQ_HDINN0	13		C	LRC_SQ_HDINN0	13		C
AN34	LRC_SQ_VCCIB0	13			LRC_SQ_VCCIB0	13		
AM33	LRC_SQ_HDINP0	13		T	LRC_SQ_HDINP0	13		T
AN33	LRC_SQ_VCCRX0	13			LRC_SQ_VCCRX0	13		
AH28	CFG2	8			CFG2	8		
AD24	CFG1	8			CFG1	8		
AJ29	CFG0	8			CFG0	8		
AF25	PROGRAMN	8			PROGRAMN	8		
AJ28	CCLK	8			CCLK	8		
AE25	INITN	8			INITN	8		
AK31	DONE	8			DONE	8		
GNDIO	GNDIO8	-			GNDIO8	-		
AE24	WRITEN***	8			WRITEN***	8		
AJ30	CS1N***	8			CS1N***	8		
AD25	CSN***	8			CSN***	8		
AG29	D0/SPIFASTN***	8			D0/SPIFASTN***	8		
VCCIO	VCCIO8	8			VCCIO8	8		
AG28	D1***	8			D1***	8		
AG30	D2***	8			D2***	8		
AH29	D3***	8			D3***	8		
GNDIO	GNDIO8	-			GNDIO8	-		
AF26	D4***	8			D4***	8		
AH30	D5***	8			D5***	8		
AE26	D6***	8			D6***	8		
AJ31	D7/SPID0***	8			D7/SPID0***	8		
VCCIO	VCCIO8	8			VCCIO8	8		
AG27	DI/CSSPI0N***	8			DI/CSSPI0N***	8		
AK32	DOUT/CSON/ CSSPI1N***	8			DOUT/CSON/ CSSPI1N***	8		
AK33	BUSY/SISPI***	8			BUSY/SISPI***	8		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
E5	ULC_SQ_REFCLKN	11		C	ULC_SQ_REFCLKN	11		C
D5	ULC_SQ_REFCLKP	11		T	ULC_SQ_REFCLKP	11		T
D6	ULC_SQ_VCCP	11			ULC_SQ_VCCP	11		
C5	ULC_SQ_HDINP2	11		T	ULC_SQ_HDINP2	11		T
D4	ULC_SQ_VCCIB2	11			ULC_SQ_VCCIB2	11		
C4	ULC_SQ_HDINN2	11		C	ULC_SQ_HDINN2	11		C
B5	ULC_SQ_VCCRX2	11			ULC_SQ_VCCRX2	11		
A5	ULC_SQ_HDOUTP2	11		T	ULC_SQ_HDOUTP2	11		T
D3	ULC_SQ_VCCOB2	11			ULC_SQ_VCCOB2	11		
A4	ULC_SQ_HDOUTN2	11		C	ULC_SQ_HDOUTN2	11		C
B4	ULC_SQ_VCCTX2	11			ULC_SQ_VCCTX2	11		
A3	ULC_SQ_HDOUTN3	11		C	ULC_SQ_HDOUTN3	11		C
C1	ULC_SQ_VCCOB3	11			ULC_SQ_VCCOB3	11		
A2	ULC_SQ_HDOUTP3	11		T	ULC_SQ_HDOUTP3	11		T
B3	ULC_SQ_VCCTX3	11			ULC_SQ_VCCTX3	11		
C3	ULC_SQ_HDINN3	11		C	ULC_SQ_HDINN3	11		C
B1	ULC_SQ_VCCIB3	11			ULC_SQ_VCCIB3	11		
C2	ULC_SQ_HDINP3	11		T	ULC_SQ_HDINP3	11		T
B2	ULC_SQ_VCCRX3	11			ULC_SQ_VCCRX3	11		
AA13	VCC	-			VCC	-		
AA14	VCC	-			VCC	-		
AA15	VCC	-			VCC	-		
AA16	VCC	-			VCC	-		
AA17	VCC	-			VCC	-		
AA18	VCC	-			VCC	-		
AA19	VCC	-			VCC	-		
AA20	VCC	-			VCC	-		
AA21	VCC	-			VCC	-		
AA22	VCC	-			VCC	-		
AB14	VCC	-			VCC	-		
AB15	VCC	-			VCC	-		
AB20	VCC	-			VCC	-		
AB21	VCC	-			VCC	-		
N14	VCC	-			VCC	-		
N15	VCC	-			VCC	-		
N20	VCC	-			VCC	-		
N21	VCC	-			VCC	-		
P13	VCC	-			VCC	-		
P14	VCC	-			VCC	-		
P15	VCC	-			VCC	-		
P16	VCC	-			VCC	-		
P17	VCC	-			VCC	-		
P18	VCC	-			VCC	-		
P19	VCC	-			VCC	-		
P20	VCC	-			VCC	-		
P21	VCC	-			VCC	-		
P22	VCC	-			VCC	-		
R13	VCC	-			VCC	-		
R14	VCC	-			VCC	-		

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AG23	VCCIO4	4			VCCIO4	4		
AK21	VCCIO4	4			VCCIO4	4		
AM19	VCCIO4	4			VCCIO4	4		
AM23	VCCIO4	4			VCCIO4	4		
AC14	VCCIO5	5			VCCIO5	5		
AC15	VCCIO5	5			VCCIO5	5		
AG12	VCCIO5	5			VCCIO5	5		
AG16	VCCIO5	5			VCCIO5	5		
AK14	VCCIO5	5			VCCIO5	5		
AM12	VCCIO5	5			VCCIO5	5		
AM16	VCCIO5	5			VCCIO5	5		
AA12	VCCIO6	6			VCCIO6	6		
AB3	VCCIO6	6			VCCIO6	6		
AB8	VCCIO6	6			VCCIO6	6		
AE3	VCCIO6	6			VCCIO6	6		
AE7	VCCIO6	6			VCCIO6	6		
AH3	VCCIO6	6			VCCIO6	6		
W3	VCCIO6	6			VCCIO6	6		
W8	VCCIO6	6			VCCIO6	6		
Y12	VCCIO6	6			VCCIO6	6		
G3	VCCIO7	7			VCCIO7	7		
K3	VCCIO7	7			VCCIO7	7		
K7	VCCIO7	7			VCCIO7	7		
N3	VCCIO7	7			VCCIO7	7		
N8	VCCIO7	7			VCCIO7	7		
P12	VCCIO7	7			VCCIO7	7		
R12	VCCIO7	7			VCCIO7	7		
T3	VCCIO7	7			VCCIO7	7		
T8	VCCIO7	7			VCCIO7	7		
AD28	VCCIO8	8			VCCIO8	8		
AG32	VCCIO8	8			VCCIO8	8		
AB12	VCCAUX	-			VCCAUX	-		
AB13	VCCAUX	-			VCCAUX	-		
AB22	VCCAUX	-			VCCAUX	-		
AB23	VCCAUX	-			VCCAUX	-		
AC13	VCCAUX	-			VCCAUX	-		
AC22	VCCAUX	-			VCCAUX	-		
M13	VCCAUX	-			VCCAUX	-		
M22	VCCAUX	-			VCCAUX	-		
N12	VCCAUX	-			VCCAUX	-		
N13	VCCAUX	-			VCCAUX	-		
N22	VCCAUX	-			VCCAUX	-		
N23	VCCAUX	-			VCCAUX	-		
A1	GND	-			GND	-		
A10	GND	-			GND	-		
A13	GND	-			GND	-		
A22	GND	-			GND	-		
A25	GND	-			GND	-		
A34	GND	-			GND	-		

Date	Version	Section	Change Summary
August 2007 (cont.)	02.8 (cont.)	DC and Switching (cont.)	sysCLOCK GPLL timing has been updated.
		Pinout Information	Added ECP2M50 (484/672/900-fpBGA), ECP2M70 (900-fpBGA) and ECP2M100 (900-fpBGA) pinout information.
		Ordering Information	1156-fpBGA package option has been removed from the LatticeECP2M family.
September 2007	02.9	Pinout Information	Added Thermal Management text section.
February 2008	03.0	Architecture	Added LVCMOS33D description.
		DC and Switching	LatticeECP2M Supply Current has been updated.
			Typical Building Block Function Performance, External Switching Characteristics, Internal Switching Characteristics, Family Timing Adders, sysCLOCK GPLL Timing, sysCLOCK SPLL Timing, DLL Timing and sysCONFIG Port Timing Specifications have been updated (timing rev. A 0.11).
			Figure 3-9. Read/Write Mode (Normal) and Figure 3-10. Read/Write Mode with Input and Output Registers have been updated.
			Table 3-8. Channel output Jitter (Max) has been updated.
		Pinout Information	Signal description has been updated.
			Added 1152-fpBGA pinouts for the ECP2M70 and ECP2M100.
April 2008	03.1	Pinout Information	Available DDR Interfaces per I/O Bank for the LFE2M35 (484/672-fpBGA) have been updated.
June 2008	03.2	Introduction	Family Selection Guide table - Updated number of EBR SRAM Blocks for the ECP2-70 device.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Clarification of the operation of the secondary clock regions.
		DC and Switching Characteristics	Removed Read-Before-Write sysMEM EBR mode.
August 2008	03.3	Architecture	Clarification of the operation of the secondary clock regions.
		Pinout Information	Added information for [LOC]DQ[num] to Signal Descriptions table.
January 2009	03.4	DC and Switching Characteristics	Updated typical and max. jitter numbers in Channel Output Jitter table for x10 mode.
			Added Channel Output Jitter table for x20 mode.
November 2009	03.5	DC and Switching Characteristics	Updated SPI/SPIm Configuration Waveforms diagram.
			Updated footnotes in LatticeECP2 Initialization Supply Current table.
			Updated footnotes in LatticeECP2M Initialization Supply Current table.
			Updated footnotes in SERDES High Speed Data Receiver (LatticeECP2M Family Only) table.
			Updated max. value for t_{DINIT} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.
			Updated Serial Output Timing and Levels table.
			Updated Figure 3-5 MLVDS
			Updated Table 3-7 Serial Output Timing and Levels
			Updated Table 3-15 Power Down/Power Up Specification
		Pinout Information	Signal Descriptions table - corrected references to ULM, URM, LRM (changed to LUM, RUM and RLM), added footnote 5.